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DJANAL USER'S MANUAL

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Final Report

Prepared for

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This document presents a brief description of the operation of DJANAL and provides comprehensive instruction for its use.		
It is assumed that the reader is familiar with the purpose and utility of the MAP and FETLOG programs; thus, no attempt is made to describe either unless it is essential to the understanding of DJANAL.		
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PREFACE

The DJANAL (DisJunct ANALyzer) program provides a means for the LSI designer to format output from the Mask Analysis Program (MAP) for input to the FETLOG (FETSIM/LOGSIM) processor.

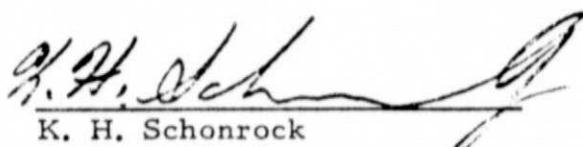
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It is assumed that the reader is familiar with the purpose and utility of the MAP and FETLOG programs; thus, no attempt is made to describe either unless it is essential to the understanding of DJANAL.

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Approved by:



K. H. Schonrock

1. INTRODUCTION

The production of DJANAL arose out of a need for a means to transform the primitive output of the MAP processor into a form suitable for use as input to the FETLOG processor. Since due to its very nature the MAP processor generates fragmentary data for each device in a design, it is required that the pieces be put together to form the more common place lumped devices traditionally used in network simulation programs. Also, more importantly, the transistor equations generated by the MAP "BOOL" command must be analyzed to isolate and characterize disjunct circuits so that the logical function of the design ultimately may be determined.

DJANAL has been designed to allow the user to inject additional devices into the network via card input so that he may include off chip loading or modify effectively the MAP generated data. A natural extension of this capability provides the facility for analyzing a network that is input manually in its entirety.

Two output files are produced by the program with an attendant listing on the printer. The first output file consists of an input file for the LOGSIM portion of the FETLOG processor. This file will consist of at least one ROM card and an accompanying NET card for each disjunct circuit in the design. The disjuncts that have more than one output will have a ROM and a NET card for each such output. The second output file consists of a collection of input decks to the FETSIM portion of the FETLOG processor. There will be one FETSIM deck for each and every disjunct circuit in the design.

DJANAL has been designed to accept parametric and excitation data in an attempt to relieve the user of the burden of injecting this data at FETLOG run time. It is anticipated that editing of DJANAL output prior to running FETLOG will be unnecessary.

2. TECHNICAL DESCRIPTION

As previously discussed, the geometric nature of the MAP processor gives rise to data that is generally unusable and difficult to interpret in terms of lumped network devices. The first goal of the DJANAL processor is to organize and format the MAP output so that the devices are recognizable in their traditional form. Transistors are organized in a gate-source/drain node list; capacitors and resistors are organized in a from-to node list. Transistor channel dimensions are determined from MAP output that describes the source/drain boundaries of the transistors and must be created in a precise form with the MAP commands. The masks that are required are illustrated in Figure 2-1 and may be produced as depicted in the sample MAP command set presented in Appendix B. The DJANAL processor will expect parallel pairs of unit wide rectangles for channel dimension calculation. Any deviation from this requirement is certain to produce erroneous results. Please note that the MAP "RANG" command is insufficient to produce channel information since the resulting output bears no distinction between channel width and channel length. As capacitors are read from the MAP file, successive capacitors between the same nodes will be added in parallel prior to being entered into the DJANAL data base. Resistors will be treated in the same manner with due regard for the different method for adding in parallel.

Once the internal representation of the network is established, DJANAL commences isolation of disjunct circuits by collecting groups of transistors having common source/drain nodes. Once a disjunct has been isolated, its output nodes are determined first by determining if any of the disjunct nodes connect to a transistor gate node of a transistor external to the disjunct and then by determining if any of the disjunct nodes have been specified as a circuit output. Once the disjunct and its output nodes have been identified, DJANAL finds the gate signal combinations that are required to connect the output to ground, the output to power, and to connect ground to power. Entries are made subsequently in a truth table according to the truth value of ground and power (negative true logic is supported) for each legal gate combination for the output being considered. Combinations that either connect ground to power or connect neither ground nor power to the output are considered illegal. Illegal combinations will have a truth table entry of indeterminate and will be resolved ultimately by the FETLOG processor.

As each disjunct is analyzed, a LOGSIM ROM card and a LOGSIM NET card is output for each output node and a FETSIM input deck is produced to represent the disjunct circuit. List output will be produced concurrent with the creation of the LOGSIM and FETSIM files to provide user insight to the results of the process.

TRANSISTOR CHANNEL MASKS

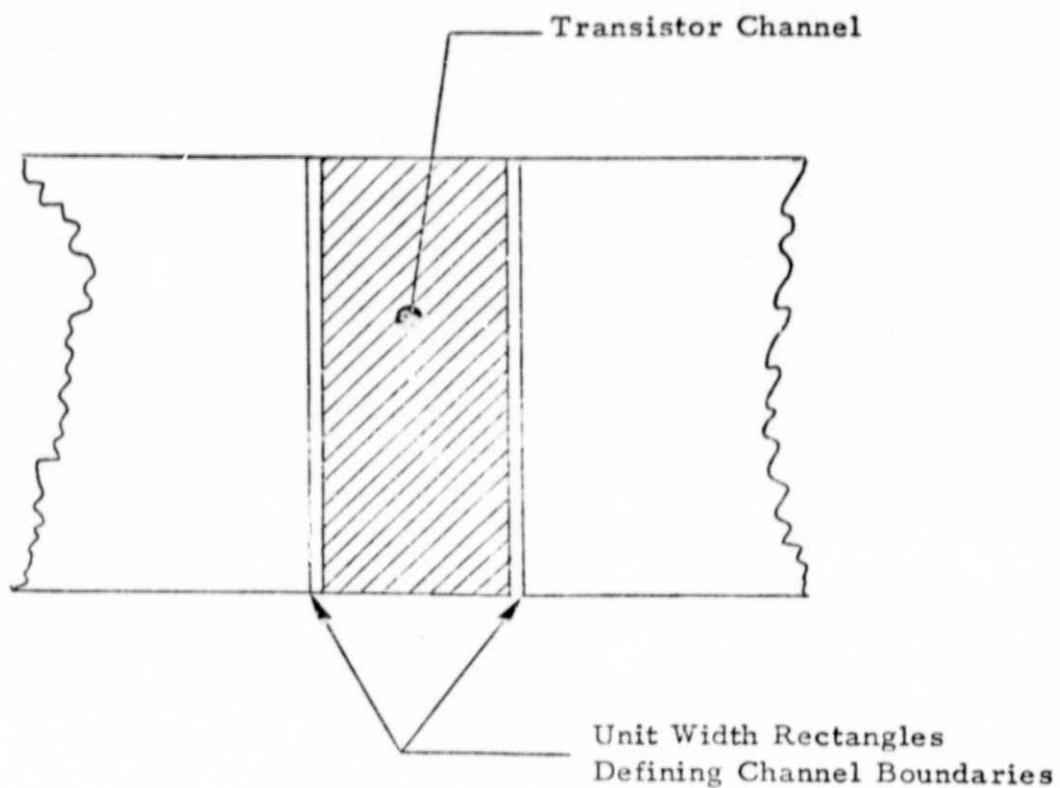


Figure 2-1

3. OPERATING INSTRUCTIONS

This section consists of instructions for preparing DJANAL input data, a description of the format and content of DJANAL output data and of job set-up instructions required to execute the program on the Sigma-5 computer. Table 3-1 presents a summary of the files utilized by DJANAL.

3.1 Input Files

Input for DJANAL consists of a control input deck and a MAP input file (optional) containing data to describe the design components and the manner in which they are interconnected and excited. Table 3-2 describes the format of the input deck and Table 3-3 describes the format of the MAP file. The MAP file must be formatted and ordered precisely as shown for DJANAL to execute properly. It is permissible to omit any of the transistor, capacitor or resistor sections of the file as long as the specified order is maintained.

3.2 Output Files

Tables 3-4 and 3-5 describe the output produced for the LOGSIM and FETSIM portions of the FETLOG processor. List output consists of error message output and of summarizing information for each disjunction analyzed. Error messages are self-explanatory and usually cause premature termination of the program.

3.3 Scratch Files

Three scratch files are utilized by DJANAL to provide temporary storage of large amounts of data. Two of these files are consecutive files and require no further discussion; the third is a random access file and must be allocated with sufficient size to accommodate the design being processed. The number of words required for this file may be determined as follows:

$$W = T \times 7 + C \times 3 + R \times 3 + E \times 20$$

where: W = Number of words required

T = Number of transistors in design

C = Number of capacitors in design

R = Number of resistors in design

E = Number of cards in excitation deck.

FILE CHARACTERISTICS SUMMARY

Logical Unit No.	Organization	Mode	Format	Contents
5	Consecutive	Input	Card Images	DJANAL CONTROL INPUT
6	Consecutive	Output	Line Images	DJANAL L,ST OUTPUT
10	Random	Scratch	Binary	
11	Consecutive	Scratch	Card Images	
12	Consecutive	Output	Card Images	FETSIM FILE
13	Consecutive	Scratch	Card Images	
14	Consecutive	Input	Card Images	MAP INPUT FILE
15	Consecutive	Output	Card Images	LOGSIM FILE

Table 3-1

DJANAL INPUT DECK

Card	Col	Format	DESCRIPTION
1. 0	1-10	A	Enter "Parameters" in CC 1-10.
1. 1	1-4	A	Process technology code: SOS - Silicon on sapphire CMOS - Metal gate CMOS. PMOS - Metal gate PMOS. NMOS - Metal gate NMOS.
	5-12	F	Threshold voltage for P-type transistors
	13-20	F	Threshold voltage for N-type transistors
1. 2*	1-6	F	Relative permittivity of silicon dioxide
	7-12	F	Relative permittivity of silicon substrate
	13-18	F	Channel mobility of electrons
	19-24	F	Channel mobility of holes
	25-33	E	Doping level of N-substrate
	34-42	E	Doping level of P-well
	43-51	E	Gate oxide thickness
	52-57	F	Saturation curve slope for N-MOS
	58-63	F	Saturation curve slope for P-MOS
	64-67	F	Mobility variation factor for N-MOS
	68-71	F	Mobility variation factor for P-MOS
1. 3			Provide "NAME" card as described on page 28 of LOGSIM User's Manual (may be omitted).
1. 4			Provide "CONT" card as described on page 28 of LOGSIM User's Manual (may be omitted).
			*Refer to FETSIM Users Manual for a complete description of these parameters.

Table 3-2

DJANAL INPUT DECK
(Continued)

Card	Col	Format	DESCRIPTION
2.0	1-11 13-15 17-26	A A E	Enter "TRANSISTORS" in CC 1-11. Enter "MAP" in CC 13-15 if transistor data is to be read from MAP file. Scale factor for MAP transistor dimension data. Must be a value that will normalize MAP data to mils.
2.1	1 2-6 7-11 12-16 17-25 26-34 35-43	A I I I F F F	P = P-type transistor N = N-type transistor Gate node number of transistor Drain node number of transistor Source node number of transistor Effective channel width of transistor (Mils) Effective channel length of transistor (Mils) Threshold voltage for transistor (required only if it is desired to override value entered in card 1.1) • • • Repeat card type 2.1 as required to define all manually input transistors.
3.0	1-10 13-15 17-26	A A E	Enter "CAPACITORS" in CC 1-10. Enter "MAP" in CC 1-10 if capacitor data is to be read from MAP file. Scale factor for MAP capacitor data. Must be a value that will normalize MAP data to picofarads.
3.1	1-5 6-10 11-22	I I E	A node to which the capacitor is connected. The other node to which the capacitor is connected. Value of capacitance (picofarads) • • • Repeat card type 3.1 as required to define all manually input capacitors.

Table 3-2
(Continued)

DJANAL INPUT DECK
(Continued)

Card	Col	Format	DESCRIPTION
4.0	1-9 13-15 17-26	A A E	Enter "RESISTORS" in CC 1-9. Enter "MAP" in CC 13-15 if resistor data is to be read from MAP file. Scale factor for MAP resistor data. Must be a value that will normalize MAP data to K-ohms.
4.1	1-5 6-10 11-22	I I E	A node to which the resistor is connected The other node to which the resistor is connected Value of resistance (K-ohms) • • •
			Repeat card type 4.1 as required to define all manually input resistors.
5.0	1-10	A	Enter "EXCITATION" in CC 1-10.
5.1	1-4	A	Time scale for simulation: "MILL" - Milliseconds "MICR" - Microseconds "NANO" - Nanoseconds "PICO" - Picoseconds
	5-10	I	Maximum simulation time in units of specified time scale
	11	A	Logic value of ground ("L" for logic low, "H" for logic high)
	12-16	I	Node to which ground is connected
	17-24	F	Supply voltage - VDD (Volts)
	25-29	I	Node to which supply voltage is connected
	30-37	F	Clock voltage - VGG (Volts)
	38-42	I	Nodes to which VGG is connected
	43-47	I	Make entries as required for 2 phase and
	48-52	I	4 phase logic
	53-57	I	

Table 3-2
(Continued)

DJANAL INPUT DECK
(Continued)

Card	Col	Format	DESCRIPTION
5.2*	1-8	F	Voltage at which a signal is to be considered as switched from the low logic state to the high logic state
	9-16	F	Voltage at which a signal is to be considered switched from the high logic state to the low logic state
	17-24	F	Voltage rate of change for which a signal is considered to be stabilized
	25-32	F	Number of digits of numerical accuracy desired for simulation
	33-40	F	Initial integration time interval
	41-48	F	Simulation dwell value for output excursion
5.3			Provide a LOGSIM "GENF" card for each clock node as specified in CC 38-57 in card no. 5.1.
5.4			Provide LOGSIM "GEN" and "GENF" cards as required to define each logic input.
6.0	1-7	A	Enter "OUTPUTS" in CC 1-7.
6.1	1-72	8A8	Enter circuit output node numbers. Repeat card 6.1 as required to define all circuit outputs.
*See FETLOG User's Manual for complete description of card 5.2 parameters.			

Table 3-2
(Continued)

MAP INPUT FILE

Card	Col	Format	DESCRIPTION
1.0	10	I	The number "6" must be present in column 10.
1.1	1-10	I	Device number
	11-20	I	Source/drain node number
	21-30	I	Drain/source node number
	31-40	I	Gate node number
	41-50	I	Device Type code: = 2 for PNP transistor ≠ 2 for NPN transistor
	51-60	I	Functional Device Code: = 0 or 1 - device is transistor ≠ 0 or 1 - device is not a trans. and will be ignored
• • •			Card type 1.1 repeated for each transistor
1.2	1-60	6I10	"-1" must be present in all fields to signal termination of transistor interconnect data.
2.0	10	I	The number "6" must be present in column 10.
2.10	1-10	I	Device number
	11-20	I	Pair number
	21-30	I	X1 - Coordinate pair defining endpoints
	31-40	I	Y1 of the diagonal of a unit wide
	41-50	I	X2 rectangle that defines edge
	51-60	I	Y2 of transistor channel
2.11	1-20	I	Device number
	11-20	I	Pair number (must match that of card 2.10)
	21-30	I	X1 - Coordinate pair defining endpoints
	31-40	I	Y1 of the diagonal of a unit wide

Table 3-3
(Continued)

MAP INPUT FILE
(Continued)

Card	Col	Format	DESCRIPTION
2.11	Cont'd) 41-50 51-60	I I	X2 rectangle that defines other Y2 edge of a transistor channel.
• •			Card types 2.10 and 2.11 repeated for each transistor
2.2	1-60	6I10	"-1" must be present in all fields to signal termination of transistor dimension data.
3.0	10	I	The number "4" must be present in column 10.
3.1	1-10 11-20 21-30 31-40	I I I I	Node number to which capacitor is connected The other node number to which capacitor is connected Whole number representing scaled capacitance Exponent (power of 10) by which capacitance (CC 21-30) is scaled
• •			Card type 3.1 repeated for each capacitor
3.2	1-60	6I10	"-1" must be present in all fields to signal end of capacitor data.
4.0	1-10	I	The number "4" must be present in column 10.
4.1	1-10 11-20 21-30 31-40	I I I I	Node number to which resistor is connected The other node number to which resistor is connected Whole number representing scaled resistance Exponent (power of 10) by which resistance is scaled
• •			Card type 4.1 repeated for each resistor
4.2	1-60	6I10	"-1" must be present in all fields to signal end of resistor data.

Table 3-3
(Continued)

LOGSIM OUTPUT FILE

Card	Col	Format	DESCRIPTION
1			"SPEC" card as described in LOGSIM User's Manual. Parameters will be automatically generated by DJANAL.
2			"NAME" card copied directly from input deck.
3			"CONT" card copied directly from input deck.
4. 0 • • 4. n			"ROM" cards specifying logical behavior of each output node of each DisJunct.
5. 0 • • 5. n			"NET" cards specifying the interconnect structure of the DisJunct circuits.
6. 0 • • 6. n			"GENF" and "GEN" cards copied directly from input deck.

Table 3-4

FETSIM OUTPUT FILE

Card	Col	Format	DESCRIPTION
1.0	1-6	F	Relative permittivity of silicon dioxide.
	7-12	F	Relative permittivity of silicon substrate.
	13-18	F	Channel mobility of electrons.
	19-24	F	Channel mobility of holes.
	25-33	E	Doping level of N substrate.
	34-42	E	Doping level of P well.
	43-51	E	Gate oxide thickness.
	52-57	F	Slope factor for N-MOS.
	58-63	F	Slope factor for P-MOS.
	64-67	F	Mobility variation factor for N-MOS.
	68-71	F	Mobility variation factor for P-MOS.
1.1	1	I	= 1 to indicate SOS; blank otherwise.
	2-5	A	Time scale code: MILL indicates milliseconds. MICR indicates microseconds. NANO indicates nanoseconds. PICO indicates picoseconds.
	6	A	"+" to indicate positive true logic. "-" to indicate negative true logic.
	8-15	A	Node to which ground is connected.
	16-21	F	Value of V_{DD} (volts).
	22-29	A	Node to which V_{DD} is connected.
	30-35	F	Value of V_{GG} (volts).
	36-43	A	Nodes to which V_{GG} is connected.
	44-51	A	entries as required for (two and four phase logic)
	52-59	A	
	60-67	A	
1.2	1-8	F	Voltage at which a signal is to be considered as switched from the "low" logic state to the "high" logic state.

Table 3-5

FETSIM OUTPUT FILE
(Continued)

Card	Col	Format	DESCRIPTION
	9-16	F	Voltage at which a signal is to be considered as switched from the "high" logic state to the "low" logic state.
	17-24	F	Voltage rate of change for which a signal is to be considered as stabilized.
	25-32	F	Number of digits of numerical accuracy desired for analog portion (FETSIM) of simulation.
	33-40	F	Initial integration time interval.
2.0	1-4	A	Circuit name.
	5-8	I	# of circuits of this type (will be set=1 by DJANAL).
	9-12	I	# of P transistors.
	13-16	I	# of N transistors.
	17-20	I	# of resistors.
	21-24	I	# of capacitors.
	25-28	I	# of input nodes.
	29-32	I	# of dependent nodes.
	33-36	I	# of output nodes.
	37-40	I	Initialization parameter (will be set=0 by DJANAL).
2.1			(Provide a type 2.1 card for each P transistor.)
	1-8	A	Gate node name.
	9-16	A	Drain node name.
	17-24	A	Source node name.
	25-33	F	Threshold voltage.
	34-42	F	Channel width (mils).
	43-51	F	Channel length (mils).
2.2			(Provide a type 2.2 card for each N transistor formatted identically as a type 2 card.)

Table 3-5
(Continued)

FETSIM OUTPUT FILE
(Continued)

Card	Col	Format	DESCRIPTION
2.3	1-8 9-16 17-25	A A F	(Provide a type 2.3 card for each resistor) From node name to node name resistance in KΩ
2.4	1-8 9-16 17-25	A A F	(Provide a type 2.4 card for each capacitor.) From node name to node name capacitance in picofarads
2.5	1-72	9A8	Output nodes of DisJunct, one name per eight column field. Repeat card type 2.5 as required to specify all output
2.6	1-72	9A8	Input nodes of Disjunct, one name per eight column field. Repeat card type 2.6 as required to specify all inputs. Repeat card types 2 as required to specify all Disjuncts in circuit.

Table 3-5
(Continued)

3.4 Sigma 5 Job Set-up Instructions

Presented below is the deck set-up required to execute DJANAL on the Sigma-5 computer using the CP-V operating system.

```
!JOB USER,ACCOUNT
!LIMIT (CORE,50),(TIME,10)
!ASSIGN F:5,(DEVICE,CR),(IN)
!ASSIGN F:6,(DEVICE,LP)
!ASSIGN F:10,(FILE,RAND),(RANDOM),(OUTIN),(RSTORE,50)
!ASSIGN F:11,(FILE,TEMP1),(OUTIN),(REL)
!ASSIGN F:12,(FILE,FETOUT),(OUT),(SAVE)
!ASSIGN F:13,(FILE,TEMP2),(OUTIN),(REL)
!ASSIGN F:14,(FILE,MAPFLE),(IN)
!ASSIGN F:15,(FILE,LOGOUT),(OUT),(SAVE)
!RUN (LMN,DJANAL)

!DATA
:
CARD INPUT DECK
:
!FIN
```

APPENDIX A

Presented is a sample run of the DJANAL software on the Sigma-5 computer. Included is the list output, the resulting LOGSIM and FETSIM files, and the control input file used to run the program.

17:13 JUL 07, 176 ID=00EF
JOB MS03, EC45001
LIMIT (CBRE,50), (TIME,10)
ASSIGN F:5, (FILE, SCAT1), (IN)
ASSIGN F:6, (DEVICE, LP)
ASSIGN F:10, (FILE, RAND), (RANDOM), (BLTIN), (RSTORE, 50)
ASSIGN F:11, (FILE, TEMP1), (BLTIN), (REL)
ASSIGN F:12, (FILE, FETBUT), (BLT), (SAVE)
ASSIGN F:13, (FILE, TEMP2), (BLTIN), (REL)
ASSIGN F:14, (FILE, MAPFLE), (IN)
ASSIGN F:15, (FILE, L8GBUT), (BLT), (SAVE)
RUN (LMN, D, ANAL)

***** DISJUNCT CIRCUIT DETECTED AND ANALYZED, DESCRIPTION FOLLOWS *****

DISJUNCT NAME: A010

P TRANSISTORS: SOURCE DRAIN GATE
4 1 7

N TRANSISTORS: SOURCE DRAIN GATE
8 4 7

CAPACITORS : FROM TO
1 4
4 7
8 4

OUTPUT NODES : 4

INPUT NODES : 7

***** LOGIC ANALYSIS *****

OUTPUT NODE : OUT= 4

GATE TERMINALS: G1= 7

TRUTH TABLE: G1 : OUT
*****:*****
0 : 1
1 : 0

*** THE FOLLOWING ROM SPECIFICATION AND NET CARD HAVE BEEN GENERATED TO SIMULATE
ROM 1 1A01110
NET 4 A011 7

***** DISJUNCT CIRCUIT DETECTED AND ANALYZED, DESCRIPTION FOLLOWS *****

DISLINCT NAME: AD20

P-TRANSISTORS: SOURCE-DRAIN-GATE

7 1 3
7 1 5
7 1 2
7 1 6

N-TRANSISTORS: SOURCE-DRAIN-GATE

NAME	STATION	DATE
11	7	6
11	10	2
10	9	5
9	8	3

CAPACITORS—FRAM

1	7
8	7
7	2
7	3
7	5
7	6
7	8
8	7
9	3
9	5
9	7
10	2
10	5
10	8
11	2
11	6
11	7
11	8

OUTPUT NODES : 7

INPUT NODES : (L) 10 2 9

***** LOGIC ANALYSIS *****

OUTPUT NAME : OUT2 7

GATE TERMINALS: G1 = 3
G2 = 5
G3 = 2
G4 = 6

THE TABLES: 61 62 63 64 : MINT

81 82 83 84 85 86 87

3 C C C ; 1

• • • • •

1 1 1 C : 1

PCL

C FET8UT T8 LP

3.90011.700 500.0 400.0.15C0E 16.1500E 16.12CCE-04 .020 .010 .000 .000

NAN8+L8 10.0001 .000000 0 0 0

9.500 .500 .010 7.000 .010 .000 .000 .000

A010 1 1 1 0 3 3 1 1 C

7 1 4 -1.500 4.605 .4C1

7 4 8 1.500 3.200 .2C1

1 4 .360

4 7 .150

8 4 .003

4

7

A020 1 4 4 0 18 6 4 1 C

3 1 7 -1.500 1.300 .4C1

5 1 7 -1.500 1.300 .4C1

2 1 7 -1.500 1.300 .4C1

6 1 7 -1.500 1.300 .4C1

6 7 11 1.500 3.600 .2C1

2 10 11 1.500 3.600 .2C1

5 9 10 1.500 3.200 .2C1

3 8 9 1.500 3.200 .2C1

1 7 .374

8 7 .150

7 2 .01

7 3 .010

7 5 .014

7 6 .135

7 8 .485

8 7 .193

9 3 .102

9 5 .102

9 7 .020

10 2 .113

10 5 .113

10 8 .485

11 2 .121

11 6 .113

11 7 .026

11 8 .485

7

3 5 2 6

APPENDIX B

Presented is a MAP command set that adequately generates the data required for DJANAL execution. Other command sets may be equally appropriate if the resulting output conforms to the standards set forth in the body of this manual.

COMM ABBREVIATED CMOS DESIGN ANALYSIS SET. REVISED: 5/76
COMM SCALE = 0.001 MIL
COMM
COMM NEGATION OF THE N MASK
OPER N = NGTV N
COMM
COMM NODAL TRACE
COMM
COMM PREPARE RECTANGLE ID'S FOR TRACE
SPEC R100,S10# 1,I10# 1,R200,S20# 1,I20# 0
OPER W = SAME W
SPEC R100,S101 W,I10# 1,R200,S20# 2,I20# 0
OPER P = SAME P
SPEC R100,S101 P,I10# 1,R200,S20# 3,I20# 0
OPER N = SAME N
SPEC R100,S101 N,I10# 1,R200,S20# 4,I20# 0
OPER T = SAME T
SPEC R100,S101 T,I10# 1,R200,S20# 5,I20# 0
OPER C = SAME C
SPEC R100,S101 C,I10# 1,R200,S20# 6,I20# 0
OPER M = SAME M
COMM
TRAC /M:C/C:M,P,N/P:C/N:C/
COMM
COMM GENERAL ARTWORK CHECKING - PHASE 1
COMM
COMM
COMM MINIMUM N-P SPACING BETWEEN DIFFERENT NODES = 0.4 MIL
SPEC PRNT,TEMP,MAXW=399
OPER NPSE = TWIX N,P DIFF
COMM MINIMUM METAL LINE WIDTH = 0.4 MIL
SPEC MAXX=399
OPER MLWX = SAME M
SPEC MAXY=399
OPER MLWY = SAME M
SPEC PRNT,TEMP
OPER MLWE = PLUS MLWX,MLWY
FREE MLWX,MLWY
COMM MINIMUM METAL-METAL SPACING = 0.3 MIL FOR LINES < 10 MILS LONG
SPEC PRNT,TEMP,MAXW=299
OPER MMSE = TWIX M DIFF
COMM MINIMUM METAL-METAL SPACING = 0.4 MIL FOR LINES > 10 MILS LONG
SPEC PRNT,TEMP,MINL=10001,MAXW=399
OPER MMSE = TWIX M DIFF
COMM MINIMUM METAL-TOX SPACING = 0.2 MIL
SPEC PRNT,TEMP,MAXW=199
OPER MTSE = TWIX M,T
COMM
COMM SEPARATION OF P DIFFUSION INTO ACTIVE OR GUARD BAND AREAS
OPER PA = NLNK P,W LINE,LINE
OPER PG = NINT P,PA
COMM SEPARATION OF N DIFFUSION INTO ACTIVE OR GUARD BAND AREAS

OPER NA = INTR N,W
 OPER NG = NINT N,NA
 COMM
 COMM MINIMUM N GUARD BAND WIDTH = 0.4 MIL
 SPEC PRNT, TEMP, MAXA=399
 OPER NWE = SAME NG
 COMM MINIMUM P GUARD BAND WIDTH OUTSIDE OF WELL = 0.6 MIL
 SPEC PRNT, TEMP, MAXA=599
 OPER PWE = NINT PG,W
 COMM WELL PERIMETER MUST MEET OR OVERLAP P GUARD BAND
 OPER WPER = EDGE W SAME
 OPER WPER = EXPN WPER 5,5
 SPEC PRNT, TEMP, MINA=10
 OPER WPER = NINT WPER,PG
 COMM N GUARD BAND MAY NOT INTERSECT P GUARD BAND
 SPEC PRNT, TEMP
 OPER NWE = INTR NG,PG
 COMM N GUARD BAND MUST TOTALLY SURROUND ALL P ACTIVE AREAS
 OPER VNG = VTWX NG SAME
 OPER VNG = LINK VNG,PA LINE,LINE
 OPER HNG = HTWX NO SAME
 OPER HNG = LINK HNG,PA LINE,LINE
 SPEC PRNT, TEMP
 OPER SURE = EXOR HNG,VNG
 FREE VNG,HNG
 COMM
 COMM P TRANSISTOR IDENTIFICATION / CHECKING
 COMM
 COMM
 COMM LOCATION OF PROSPECTIVE P CHANNELS
 SPEC MAXW=1000, R100, S10# 1, R200, S20# 1
 OPER PPC = TWIX PA DIFF
 SPEC MINA=100
 OPER PC = INTR PPC,T
 SPEC MINA=100
 OPER PC = INTR PC,M
 OPER QPC = LINK PPC,PC NONE,AREA
 SPEC R101, S10# 1
 OPER QPC = LINK QPC LINE
 FREE PPC,PC
 COMM MINIMUM P CHANNEL LENGTH = 0.3 MIL, WIDTH = 0.7 MIL
 SPEC MAXW=299, MAXL=699
 OPER PCE = TWIX PA DIFF
 SPEC PRNT, TEMP
 OPER PCE = LINK PCE,QPC NONE,AREA
 COMM MINIMUM THIN OXIDE WIDTH OUTSIDE EDGES OF P CHANNELS = 0.2 MIL
 OPER PCE = EXPN QPC 200,200
 SPEC PRNT, TEMP
 OPER PCE = NINT PCE,T
 COMM MINIMUM METAL WIDTH OUTSIDE EDGES OF P CHANNELS = 0.1 MIL
 OPER PCE = EXPN QPC 100,100
 SPEC PRNT, TEMP
 OPER PCE = NINT PCE,M
 COMM
 COMM LOCATION OF P SOURCES AND DRAINS
 SPEC R100, S10# 1
 OPER PSD = SAME PA
 OPER PSD = LINK PSD,QPC LINE,LINE
 OPER PSD = INTR PSD,PA

COMM
COMM P SOURCE AND DRAIN MINIMUM WIDTH = 0.1 MIL
SPEC PRNT,TEMP,MAXA=99
OPER PSDE = SAME PSD
COMM MINIMUM SPACING OF TOX TO OUTSIDE P SOURCE/DRAIN EDGES = 0.1 MIL
OPER PSDE = EXPN PSD 5,5
SPEC PRNT,TEMP,MAXA=104
OPER PSDE = NINT PSDE,T
COMM
COMM LOCATION OF P CHANNEL GATE METAL
SPEC R100,S1@# 1
OPER PGM = SAME M
OPER PGM = LINK PGM, QPC LINE, AREA
OPER PGM= INTR PGM, M
COMM
COMM MINIMUM P CHANNEL GATE METAL OVERLAP ON N GUARD BAND = 0.2 MIL
OPER PGME = EXPN NG 50,50
SPEC PRNT,TEMP,MAXA=249
OPER PGME= INTR PGM,PGME
COMM P CHANNEL GATE MUST CROSS N GUARD BAND EDGE BEFORE THICK OX. STEP
OPER PGME = LINK T,NG LINE,LINE
OPER PGME = TWIX NG,PGME
SPEC PRNT,TEMP
OPER PGME = INTR PGM,PGME
COMM
COMM N TRANSISTOR IDENTIFICATION / CHECKING

COMM
COMM LOCATION OF PROSPECTIVE N CHANNELS
SPEC MAXW=1000,R1@0,S1@# 1,R2@0,S2@# 1
OPER PNC = TWIX NA DIFF
SPEC MINA=100
OPER NC = INTR PNC,T
SPEC MINA=100
OPER NC = INTR NC,M
OPER QNC = LINK PNC,NC NONE, AREA
SPEC R1@1,S1@1 QPC
OPER QNC = LINK QNC LINE
FREE PNC,NC
COMM
COMM MINIMUM N CHANNEL LENGTH = 0.3 MIL, WIDTH = 0.7 MIL
SPEC MAXW=299,MAXL=699
OPER NCE = TWIX NA DIFF
SPEC PRNT,TEMP
OPER NCE = LINK NCE-QNC NONE, AREA
COMM MINIMUM TOX WIDTH OUTSIDE EDGES OF N CHANNELS = 0.2 MIL
OPER NCE = EXPN QNC 200,200
SPEC PRNT,TEMP
OPER NCE = NINT NCE,T
COMM MINIMUM METAL WIDTH OUTSIDE EDGES OF N CHANNELS = 0.1 MIL
OPER NCE = EXPN QNC 100,100

SPEC PRNT,TEMP
OPER NCE = NINT NCE,M
COMM
COMM LOCATION OF N SOURCES AND DRAINS
SPEC R100,S10# 1
OPER NSD = SAME NA
OPER NSD = LINK NSD,QNC LINE,LINE
OPER NSD = INTR NSD,NA
COMM
COMM N SOURCE AND DRAIN MINIMUM WIDTH = 0.1 MIL
SPEC PRNT,TEMP,MAXA=99
OPER NSDE = SAME NSD
COMM MINIMUM SPACING OF TOX TO OUTSIDE N SOURCE/DRAIN EDGES = 0.1 MIL
OPER NSDE = EXPN NSD 5,5
SPEC PRNT,TEMP,MAXA=104
OPER NSDE = NINT NSDE,T
COMM
COMM LOCATION OF N CHANNEL GATE METAL
SPEC R100,S10# 1
OPER NGM = SAME M
OPER NGM = LINK NGM,QNC LINE,LINE
OPER NGM = INTR NGM,M
COMM
COMM MINIMUM N CHANNEL GATE METAL OVERLAP ON P GUARD BAND = 0.2 MIL
OPER NGME = EXPN PG 50,50
SPEC PRNT,TEMP,MAXA=249
OPER NGME = INTR NGM,NGME
COMM N CHANNEL GATE MUST CROSS P GUARD BAND EDGE BEFORE THICK OX. STEP
OPER NGME = LINK T,PG LINE,LINE
OPER NGME = TWIX NG,NGME
SPEC PRNT,TEMP
OPER NGME = INTR NGM,NGME
COMM
COMM GENERAL ARTWORK CHECKING - PHASE 2

COMM MINIMUM SPACING BETWEEN P NON-SOURCE/DRAIN NODE AND ANY OTHER P
COMM NODE = 0.4 MIL
OPER PNSD = NINT P,PSD
SPEC PRNT,TEMP,MAXW=399
OPER PPSE = TUIX PNSD,P DIFF
COMM
COMM MINIMUM SPACING BETWEEN N NON-SOURCE/DRAIN NODE AND ANY OTHER N
COMM NODE = 0.4 MIL
OPER NNSD = NINT N,NSD
SPEC PRNT,TEMP,MAXW=399
OPER NNSE = TWIX NNSD,N DIFF
COMM
COMM MINIMUM CONTACT WIDTH = 0.3 MIL, LENGTH = 0.4 MIL
SPEC MINA=300
OPER CS = SAME C
SPEC PRNT,TEMP
OPER CSE = NINT C,CS

SPEC PRNT,TEMP,MAXA=399
OPER CSE = SAME CS
FREE CS
COMM MINIMUM SEPARATION OF STEPPED OX. AND CONTACT OPENING = 0.1 MIL
OPER EXC = EXPN C 100,100
SPEC PRNT,TEMP
OPER CTOE = NINT EXC,T
FREE EXC
COMM MINIMUM SEPARATION OF CONTACT OPENING TO SOURCE/DRAIN = 0.2 MIL
OPER SD = PLUS PSD,NSD
SPEC PRNT,TEMP,MAXA=199
OPER SDCE = NINT SD,C
COMM METAL MUST COVER SOURCE/DRAIN CONTACT OPENINGS
OPER SDC = LINK C,SD LINE,AREA
SPEC PRNT,TEMP
OPER MCDE = NINT SDC,M
COMM MINIMUM METAL OVERLAP OVER EDGE OF OTHER CONTACTS = 0.2 MIL
OPER OC = NINT C,SDC
OPER EXOC = EXPN OC 200,200
SPEC PRNT,TEMP
OPER MCDE = NINT EXOC,M
FREE SDC,OC,EXOC,PNSD,NNSD
COMM MINIMUM PENETRATION OF TOX IN GUARD BAND FOR GATE CROSS = 0.2 MIL
OPER GM = PLUS PGM,NGM
OPER GB = PLUS PG,NG
OPER TOXE = INTR GM,GB
SPEC PRNT,TEMP,MAXA=199
OPER TOXE = INTR T,TOXE
FREE GM,GB
COMM MINIMUM SEPARATION BETWEEN TOX AND OUTSIDE SOURCE/DRAIN = 0.2 MIL
SPEC PRNT,TEMP,MAXW=199
OPER TOXE = TWIX T,SD
COMM MINIMUM SEPARATION OF TOX AND OUTSIDE METAL = 0.2 MIL
SPEC PRNT,TEMP,MAXW=199
OPER TOXE = TWIX T,M
COMM
COMM EQUATION GENERATION
COMM
COMM
SPEC E201
OPER PG = SAME PG
SPEC E201
OPER NG = SAME NG
BOOL /6/PG:0/NG:1/PSD:PSD,'PGM/NSD:NSD,NGM/
COMM
COMM CALCULATION OF CHANNEL DIMENSIONS
COMM
COMM
SPEC E201
OPER OC = PLUS QPC,QNC
SPEC R100

OPER QC = EXPN QC 1,1
SPEC E201
OPER SD= SAME SD
OPER QC = INTR SD, QC SAM2
SPEC MAXX=1,MAXY=1
OPER Q = SAME QC
OPER QC = NINT QC,Q
FREE Q
FILE 6,0,QC
FREE QC
FREE SD
COMM
COMM CAPACITANCE CALCULATION
COMM
COMM EXPAND AND COMBINE DIFFUSIONS
OPER EXP = EXPN P 50,50
OPER EXN = EXPN N 50,50
OPER DIFF = PLUS EXP,EXN
COMM CATEGORIZE METAL BY TOX
OPER MTHN = INTR M,T
OPER MTHK = NINT M,MTHN
OPER MTHN = NINT MTHN,C
COMM
COMM SETUP JUNCTION CAPACITANCE-SCALED MASKS
OPER JCA = SCAL EXP 7,-2
OPER JCHE = HEDG EXP
OPER JCHE = EXPN JCHE 1,50
OPER JCVE = VEDG EXP
OPER JCVE = EXPN JCVE 50,1
OPER CAP = PLUS JCVE,JCHE
OPER CAP = PLUS CAP,JCA
OPER CAP = LINK CAP,NG NONE,POIN
FREE JCA,JCHE,JCVE,EXP,EXN
COMM
COMM SETUP CROSSOVER CAPACITANCE-SCALED MASKS
OPER DTHK = INTR DIFF,MTHK
OPER DTHN = INTR DIFF,MTHN
OPER DTHN = SCAL DTHN 10,1
OPER CAP = PLUS CAP,DTHK
OPER CAP = PLUS CAP,DTHN
FREE DTHK,DTHN
COMM
COMM SETUP SUBSTRATE CAPACITANCE-SCALED MASKS
OPER STHK = NINT MTHK,DIFF
OPER STHK = LINK STHK,NG NONE,POIN
OPER STHN = NINT MTHN,DIFF
OPER STHN = SCAL STHN 10,1
OPER STHN = LINK STHN,NG NONE,POIN
OPER CAP = PLUS CAP,STHK
OPER CAP = PLUS CAP,STHN
COMM
COMM GENERATE CAPACITANCE VALUES
AREA 6,CAP,-50000
FREE DIFF,MTHK,MTHN,STHK,STHN,CAP